

RECEIVED
CENTRAL FAX CENTER

OCT 04 2005

PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In the PATENT APPLICATION of:

Jack Wang et al.

Application No.: 10/717,447

Our File: OP-092000289

Filed: November 21, 2003

Date: October 4, 2005

For: Heat Dissipating Device Having
Improved Fastening Structure

Group: 2835

Examiner: Chervinsky, Boris Leo

PETITION TO WITHDRAW HOLDING OF ABANDONMENT UNDER 37 CFR 1.181

Mail Stop: Issue Fee
Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Sir:

This is a petition to the Commissioner to withdraw holding of abandonment for the above-referenced application.

The Notice of Abandonment dated August 4, 2005 has been received which states Applicants' failure to timely file a proper reply to the Office letter mailed on April 19, 2005. However, according to the enclosed evidence, Applicants should have timely responded the Office letter on May 3, 2005.

Therefore, the undersigned respectfully requests that the abandonment should be withdrawn and the certified patent document can be issued.

Respectfully submitted

<u>Jack Wang</u>	<u>Jack Wang</u>	<u>10/01/2005</u>
Name of sole or first inventor	Signature	Date
<u>Cheng-Hua Cheng</u>	<u>Cheng-hua Cheng</u>	<u>10/01/2005</u>
Name of second inventor, if any	Signature	Date
<u>Michael Lin</u>	<u>Michael Lin</u>	<u>10/01/2005</u>
Name of third inventor, if any	Signature	Date
<u>Charles Ma</u>	<u>Charles Ma</u>	<u>10/01/2005</u>
Name of fourth inventor, if any	Signature	Date

DATE: May 3, 2005
DOCKET NO.: OP-092000289

APPLICANT(S): Jack Wang
SERIAL NO.: 10/717,447

FILED: Nov. 21, 2003

FOR: Heat Dissipating Device Having Improved Fastening Structure
RE: Reply to Notice of Drawing Inconsistency with Specification

PAPERS FILED:

1. Front page
2. Replacement specification (1 page)



Oct 04 05 04:36p

Jimmy HDLS

RECEIVED 7035914934
CENTRAL FAX CENTER

p. 4

OCT 04 2005

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Group Art Unit: 2835
Examiner: Chervinsky, Brois Leo

In Re PATENT APPLICATION OF:

Applicant(s) :	Jack Wang)	
)	
Serial No. :	10/717,447)	
)	REPLACEMENT
Filed :	Nov. 21, 2003)	SPECIFICATION
)	
For :	Heat Dissipating Device Having Improved)	
	Fastening Structure)	
)	
Docket NO. :	OP-092000289)	_____

Mail Stop Issue Fee
Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Sir:

According to your notice of drawing inconsistency with specification, Figures 7 is listed in the amended brief description of the drawings in the specification.

Certificate of Transmission under 37 CFR 1.8

I hereby certify that this correspondence is being mailed to the United State Patent and Trademark Office.

May 3, 2005
Date


Chun-Ming Shih

Figure 2 shows a perspective view of the fastening structure as shown in Figure 1;

Figure 3 shows an exploded view of applying the fastening structure as shown in Figure 1 to a heat sink;

5 Figure 4 shows a perspective view of the application as shown in Figure 3;

Figure 5 shows another embodiment of the fitting column as shown in Figure 1; and

Figure 6 shows another modification of the fitting column.

Figure 7 shows still another modification of the fitting column.

DETAILED DESCRIPTION OF THE INVENTION

10 Reference will now be made in detail to the preferred embodiments of the present invention, examples of which are illustrated in the accompanying drawings. Wherever possible, the same reference numbers are used in the drawings and the description to refer to the same or like parts.

15 Figures 1 and 2 show the exploded view and perspective view of a fastening structure used for fitting a heat sink to a heat generating device. The fastening structure includes a back plate 10 and a plurality of fitting columns 20.

The back plate 10 is fabricated from metal, plastic or other materials. The back plate 10 is placed underneath a motherboard of a computer. In this embodiment, the back plate 10 is substantially rectangular. The back plate 10 20 includes two elongate slots 13 formed along two elongate sides thereof and two T-shape slots 13 form at two transverse sides between the elongate sides. Between the T-shape slots 13 and the transverse sides, the back plate 10 further includes a plurality of through holes 12. The through holes 12 are hexagonal, rectangular, circular, triangular or other polygonal according to specific 25 requirement.

Preferably, the fitting columns 20 are fabricated from metal materials. Each of the fitting columns 20 includes an elongate tube 24 which has a